

# T-4909-AE



For the past 40 years, Dr. Tresky AG has been perfecting the art of creating die bonding / pick & place systems.

The **T-4909-AE anniversary edition** is a manual, budget sensitive die bonder with superior ergonomic design. As with all of Tresky's products, the **T-4909-AE** incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height. Bonding parameters and sequences, intuitively programmable by an integrated Raspberry PC with touchscreen.

## T-4909-AE Application Packages:

- Epoxy
- Eutectic
- Flip-Chip

Force controlled

True Vertical Technology™

Easy to use

MICRO ASSEMBLY

T-4909-AE



# TRESKY

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Excellent performance, ergonomically designed and high reliability makes the **T-4909-AE** ideal for small and medium volume production.

#### APPLICATIONS

Die Attach, Flip-Chip, MEMS, MOEMS, VCSEL, RFID, Adhesive Bonding, Eutectic Bonding, .....

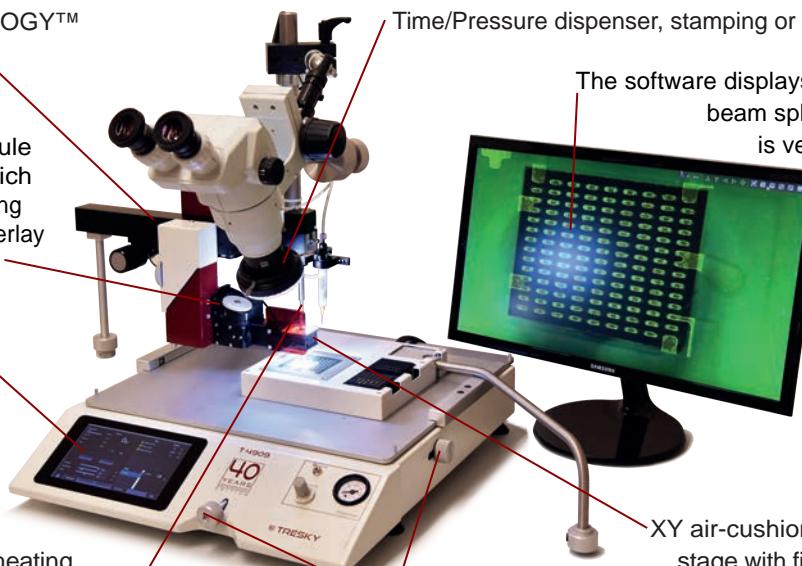
#### FEATURES AND OPTIONS

TRUE VERTICAL TECHNOLOGY™  
with 95mm Z-movement

**FLIP-CHIP ULTRA** module  
is a beam splitter optics, which  
allows the simultaneous viewing  
of two objects by an optical overlay  
(superposition) on the monitor.  
(Option)

Touchscreen for selection  
of pick & place, dispensing,  
stamping, .... mode.  
Create and store custom  
sequence.  
E.g.: Pick, dispense and  
place with automatic start of heating.

Pick & place spindle with force sensor  
and 360° tool rotation. Optional: with tool heating and Scrub



Time/Pressure dispenser, stamping or preform spindle

The software displays the overlaid  
beam splitter image and  
is very easy to use.

XY air-cushioned placement  
stage with fine adjustment  
control, supporting: Waffle- / Gel-Pak -  
Substrate - Holder, various  
Heating Plates.

#### TECHNICAL DATA

XY- Movement (placement stage):	180mm x 180mm (manual)
Z- Movement:	95mm (manual)
Spindle Rotation:	360° (unlimited)
Bond Force:	20g - 1000g
Placement accuracy:	±10µm (operator/process depending)
Flip-Chip Placement accuracy:	±5µm Option (operator/process depending)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	755mm x 730mm x 500mm
Weight:	33kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

Represented by



Headquarters

[www.tresky.com](http://www.tresky.com)

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